

Thermal Conductive Paste H2

The H2 thermal conductive paste with a heat transfer coefficient of 0,88 W/mK, silicon compound facilitates the transfer of heat between electronic components and the radiator. It is essential to the proper operation of all kinds of temperature sensors, protects against weathering, prevents thermal breakdowns. It is characterized by a very good chemical resistance to oxidation; the effect of aqueous solutions of acids, alkali and salts; sulphur dioxide and ammonia. It has a wide operating temperature range: from - 50 °C to 250 °C. Does not conduct electricity.

Physicochemical properties	
Density at 20 °C	2,7 g/cm ³
Flash point	350 °C
Solidification point	-50 °C
Refractive index	1,41
Specific heat at 50 °C	0,24 Cal/g K
Thermal conductivity	0,88 W/mk
Dielectric constant at 100 Hz	4,7(±0,1)
Volume resistance	5x10 ¹⁴ Ohm x cm
Tangent of the angle of the dielectric loss index at f=100 Hz	0,020 (±0.003)
Operating temperature range	-50 to 250 °C

Application:

- units modules with a high heat transfer coefficient,
- cooling devices on terminal boards and frames,
- flash memory drives and high-speed drives,
- motor control systems (automotive industry),
- hard disc and DVD drives,
- power transducers,
- high-power LED diodes,
- notebooks and office computers,
- network communication devices,
- household appliances, electronic and electrical components,
- air conditioning devices.

Packagings:

Volume	Type of packaging	Collective packaging	Item Code
800g	cartridge	2	ART.AGT-309
5kg	plastic container	1	ART.AGT-318

Warehousing:

Store in a well-ventilated, cool and dry place. Keep containers tightly closed when not in use. Protect from sunlight and do not expose to temperatures exceeding 50 °C.

Data contained in this document are consistent with the current state of our knowledge. They describe typical product properties and applications. However, it is up to the user to examine the suitability of this product for specific applications. We deny liability for the obtained results on the grounds that application conditions lie beyond our control.